

F I G. 1

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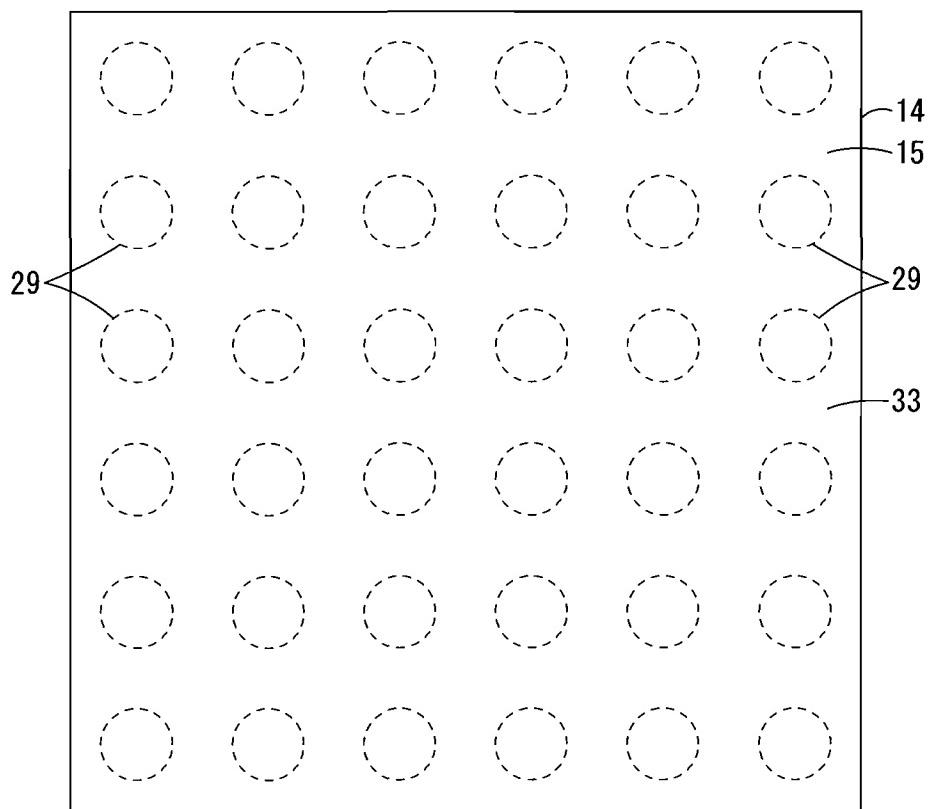


FIG. 2

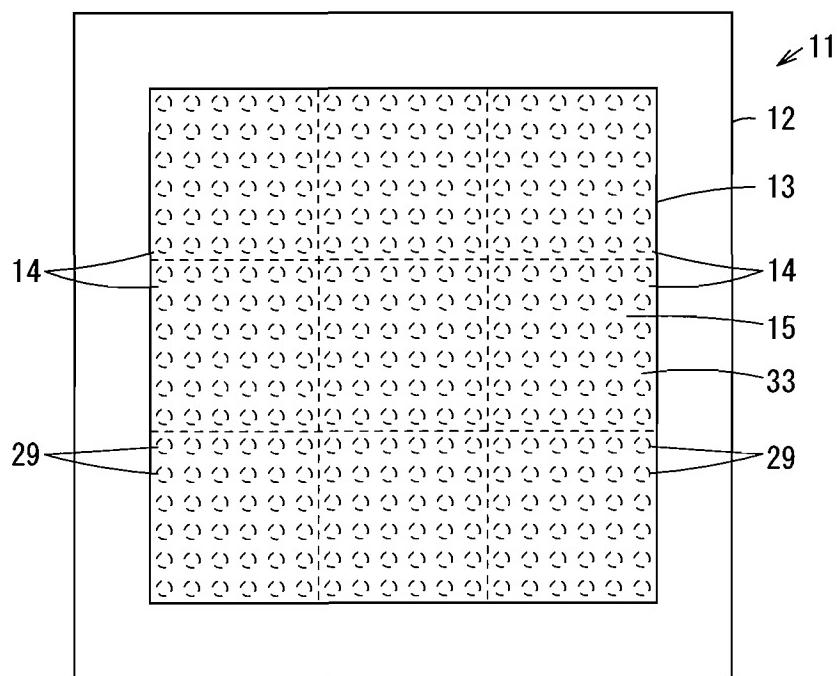
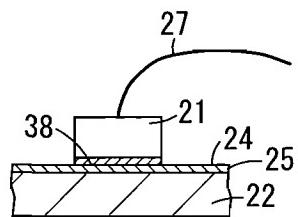


FIG. 3

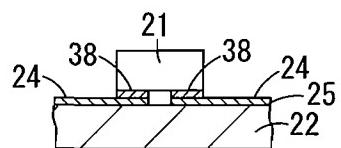
ARRANGEMENT	COMBINATION EXAMPLE 1	COMBINATION EXAMPLE 2	COMBINATION EXAMPLE 3	COMBINATION EXAMPLE 4
LENS	ENGINEERING PLASTIC (100 TO 130°C)	ACRYLIC RESIN (120°C)	POLYPROPYLENE (110°C)	
ADHESIVE AGENT (THIRD INSULATING LAYER)	THERMOSETTING RESIN			
REFLECTOR	ENGINEERING PLASTIC (100 TO 130°C)	GLASS EPOXY RESIN	ALUMINUM	ALUMINUM NITRIDE
ADHESIVE AGENT (SECOND INSULATING LAYER)	THERMOSETTING RESIN			
CONDUCTIVE PATTERN	Au/Ni/Cu			
ADHESIVE AGENT (FIRST INSULATING LAYER)	THERMOSETTING RESIN			
SUBSTRATE	ALUMINUM	GLASS EPOXY RESIN	ALUMINUM NITRIDE	
LED	GaN-BASED LED			
DIE BONDING	Ag PASTE (150°C)	Au/Sn	Au	

FIG. 4

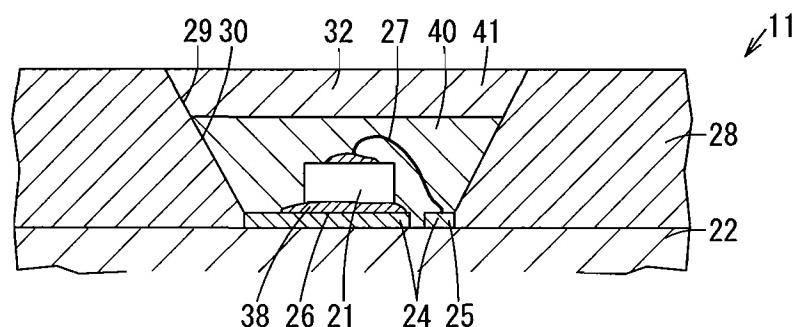
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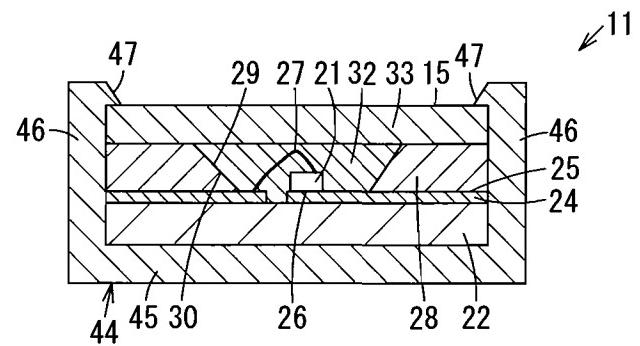
F I G. 5



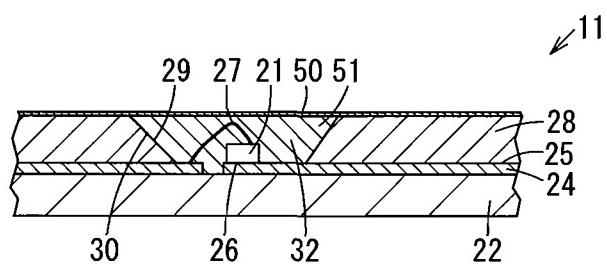
F I G. 6



F I G. 7

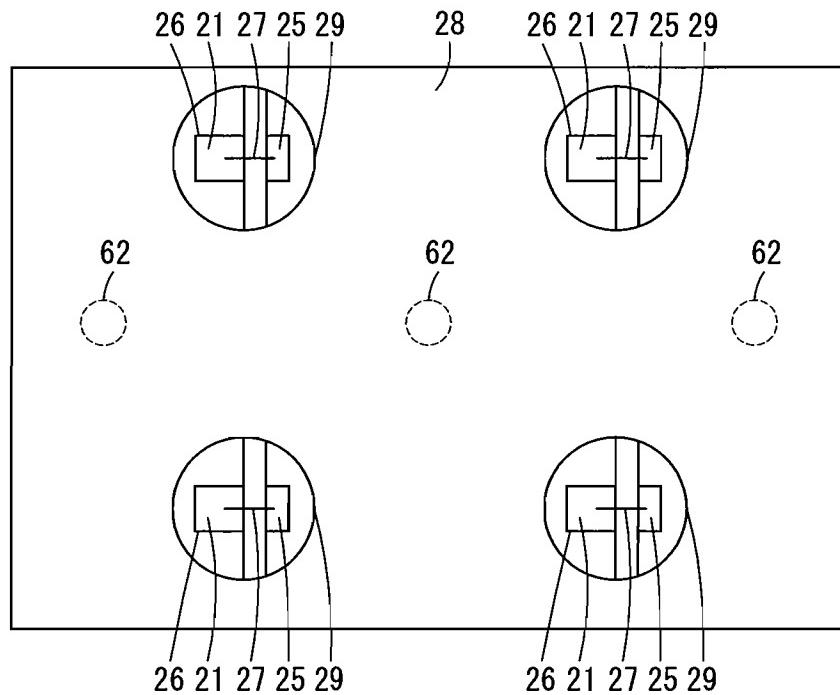


F I G. 8



F I G. 9

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F I G. 10

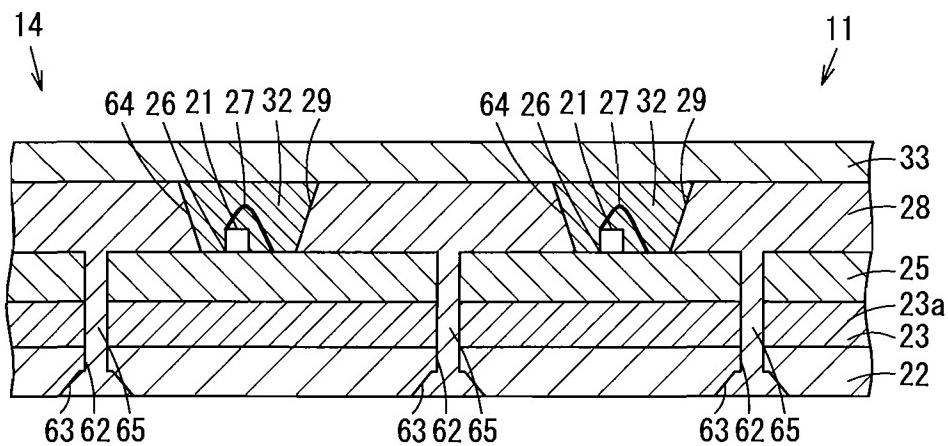


FIG. 11

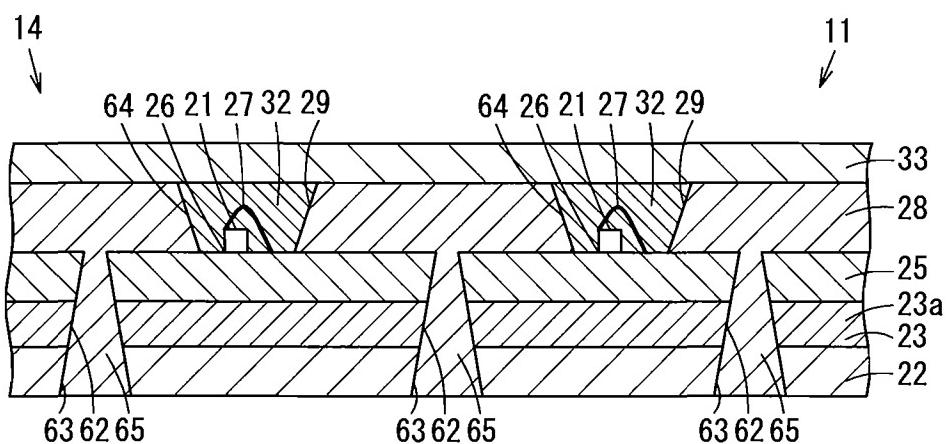


FIG. 12

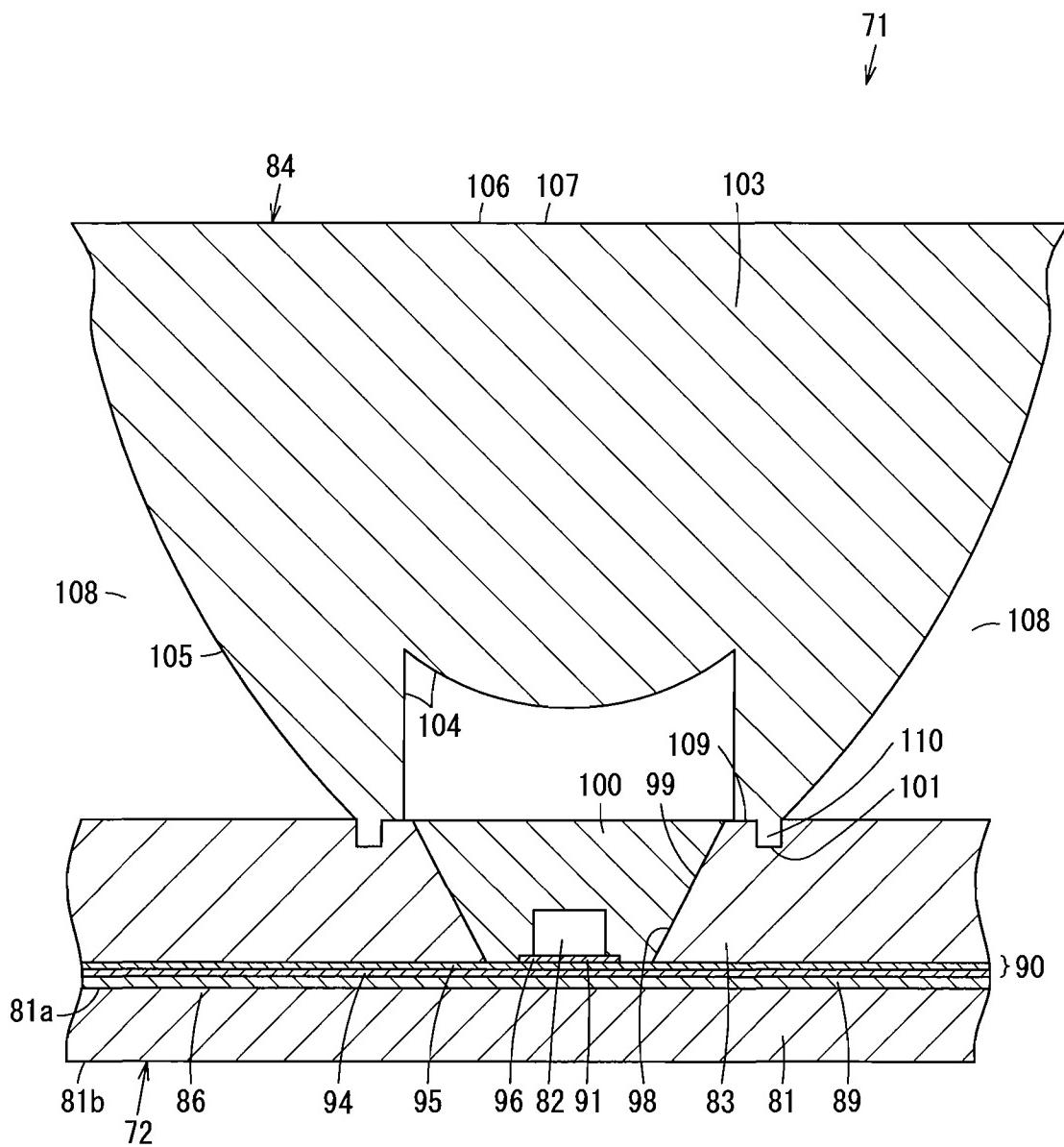


FIG. 13

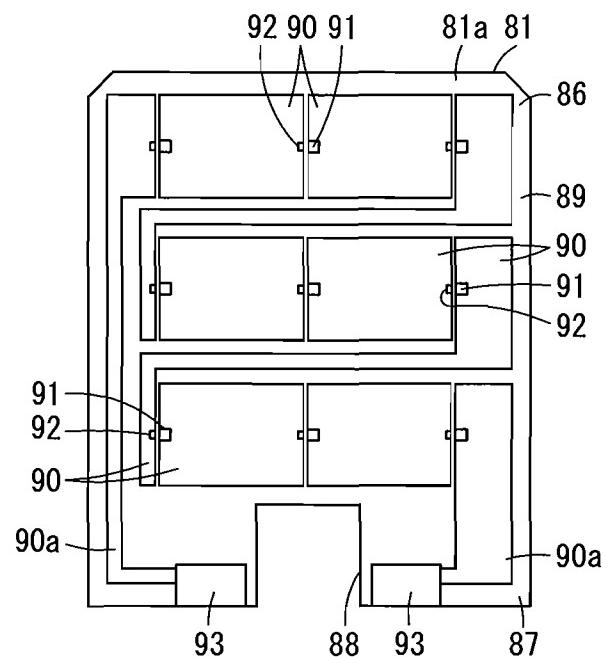


FIG. 14

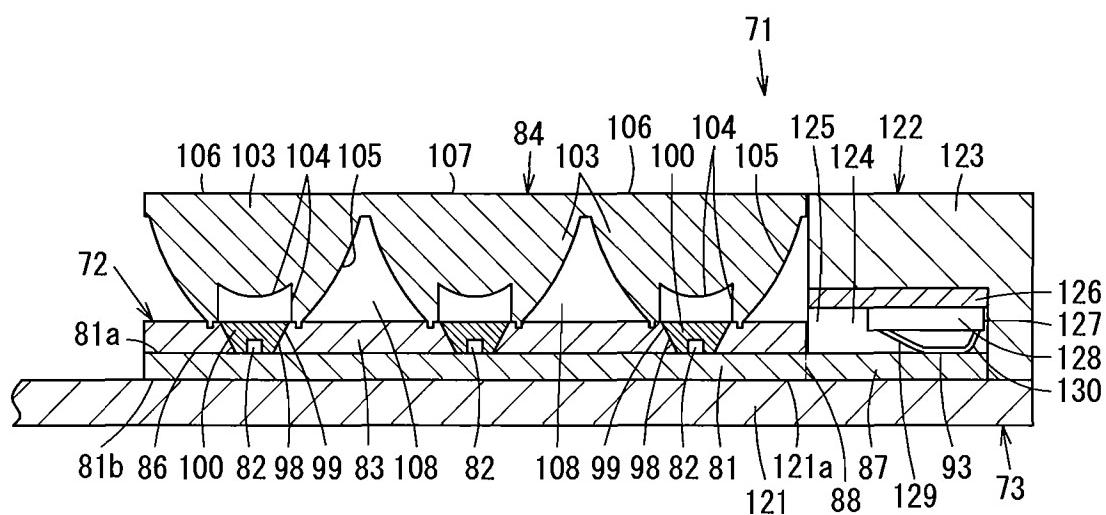
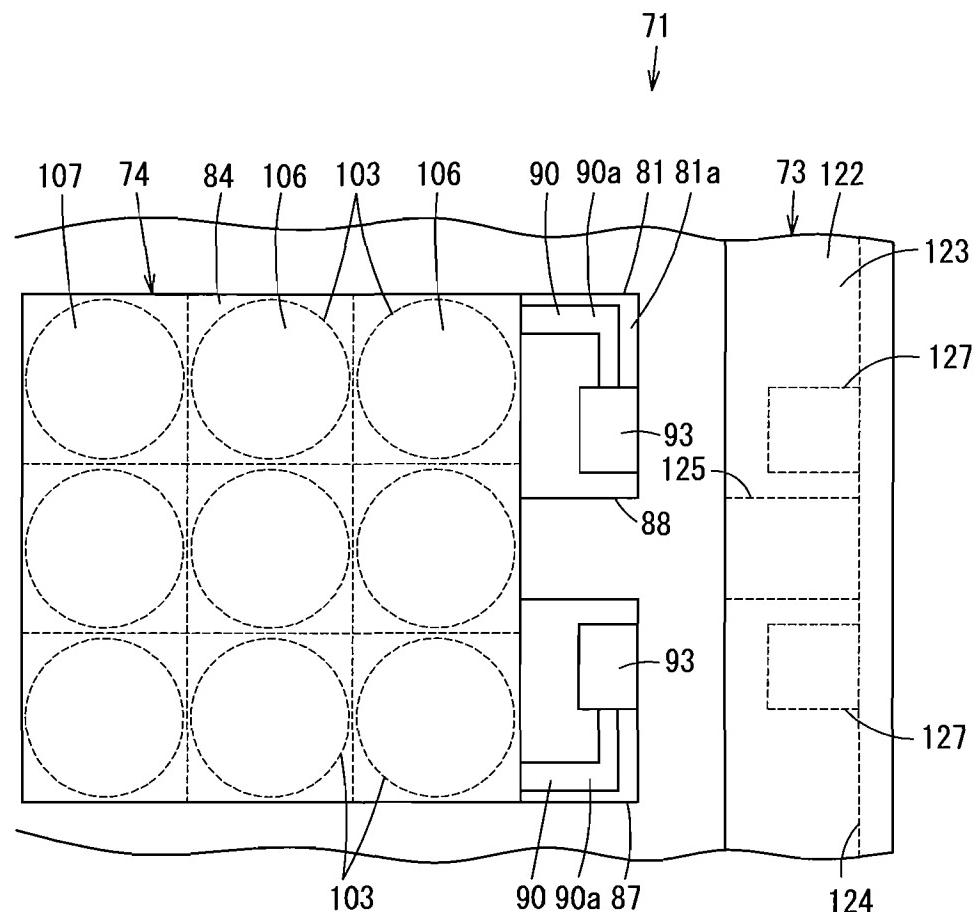


FIG. 15

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F I G. 1 6